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## APPLICANTS

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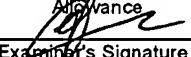
\*\* CONTINUING DATA \*\*\*\*

\*\* FOREIGN APPLICATIONS \*\*\*\*

CHINA 200310122967.9 12/30/2003

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 05/07/2004

Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Arbitration	COUNTRY	DRAWING	CLAIMS	CLAIMS
Verified and Acknowledged	 Examiner's Signature  Initials	CHINA	3	18	2

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## TITLE

Method and device for manufacturing bonding pads for chip scale packaging

FILING FEE	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue )
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